

Product / Process Change Notice

Extent of Change:

Chip process CP305, NPN silicon transistor wafers and bare die.

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The CP305 wafer process has been discontinued and replaced with the CP306V wafer process. See figures 1 and 2 for details.

Reason for Change:

New wafer process provides an improved and consistent yield.

Effect of Change:

The wafer process meets all electrical specifications of the individual devices listed on the following page.

Effective Date of Change:

December 1, 2017

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Qualification Tests:

Test	Condition	Failure rate
Resistance to Solder Shock	T = 260°C ± 5°C Dwell time = 10 sec. JESD22-B106	0/77
High Temperature Storage Life/ bake test.	150°C (-0/+10)°C, 1000 hours. JESD22-A103	0/77
Temperature Cycling	T = -65°C to +150°C 1000 cycles. Dwell time = 15 min. JESD22-A104	0/77
High Temperature Reverse Bias (HTRB)	T = 125°C, t = 48 hours, 80% MAX rated VCB JESD22-A108	0/77
Highly Accelerated Temperature and Humidity Stress Test (HAST)	T = 130°C, RH = 85%, P = 33.3 psia, and t = 96 hours. Bias conditions per device specification sheet. JESD22-A110	0/77
Accelerated Moisture Resistance Unbiased Autoclave	Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 205kPa, 29.7 psia. t = 48 hours JESD22-A102	0/77

PCN # 162
Notification Date:
December 7, 2017

Figures:

Figure 1: CP305 Chip Geometry (Discontinued)

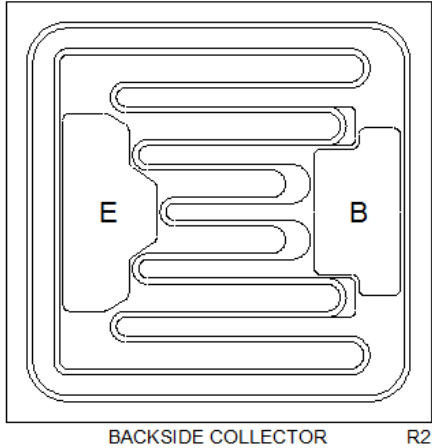
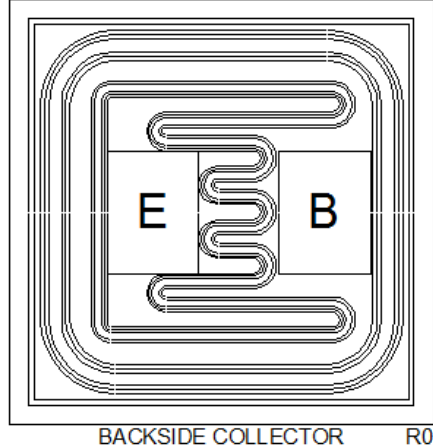


Figure 2: CP306V Chip Geometry



Wafer Diameter: 4 inch
Die Size: 31 x 31 mils
Die Thickness: 9.0 mils
Bond Pad Size (Emitter): 6.5 x 13.8 mils
Bond Pad Size (Base): 5.9 x 11.8 mils
Topside Metal: Al (30,000Å)
Backside Metal: Au (18,000Å)

Wafer Diameter: 5 inch
Die Size: 27.56 x 27.56 mils
Die Thickness: 7.1 mils
Bond Pad Size (Emitter): 5.9 x 7.9 mils
Bond Pad Size (Base): 5.9 x 7.9 mils
Topside Metal: Al-Si (30,000Å)
Backside Metal: Au (9,000Å)

Part Numbers Affected:

CP305-2N3019-CT
CP305-2N3019-CT20
CP305-2N3019-WR
CP305-2N3700-CT



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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	